

New “Process Technology Center” for semiconductor manufacturing process research and development established

New facility will enable Screen to further refine its outstanding wafer cleaning technology

The Semiconductor Equipment Company (President: Eiji Kakiuchi) of Dainippon Screen Mfg. Co., Ltd. (Headquarters: Kyoto, Japan) has completed preparations for the opening of its new Process Technology Center, a facility dedicated to cutting edge semiconductor manufacturing process and equipment research and development, located on the grounds of Screen’s Hikone Plant (480-1 Takamiya-cho, Hikone, Shiga Prefecture). The facility will commence operations on April 1, 2008.

The Process Technology Center features a dedicated clean room that will be used to develop new manufacturing processes and equipment, as well as equipment suitable for a wide range of experiments. The center will function as a base for a variety of research and development activities that will support the establishment of next-generation processes, from small-scale experiments designed to evaluate and analyze the capabilities of new processes to continuous processing of 300-mm wafers to ensure consistent process results. The environment at the center is suitable for both process demonstrations and joint R&D efforts involving device manufacturers, research institutions, and chemical and parts manufacturers, which should help speed the efficiency of cutting-edge process development. The Process Technology Center is located next to Screen’s Fab. FC-1 and FC-2 centers for the manufacturing of semiconductor cleaning equipment. The close and rapid exchange of information between R&D and production teams will ensure the timely incorporation of cutting-edge technology in production equipment.

Through the establishment of the Process Technology Center, Screen looks forward to further increasing consumer confidence in its equipment, which already has the top share in the market worldwide, while improving the company’s ability to develop innovative semiconductor manufacturing technology and meet users’ varied needs. Screen’s ultimate goal is to ensure even greater customer satisfaction through process technology that far exceeds that of its competitors.



Process Technology Center

Please download the photo from
<http://www.screen.co.jp/press/nr-photo/indexE.html>

Process Technology Center Overview

Name:	Hikone Plant Process Technology Center
Location:	480-1 Takamiya-cho, Hikone, Shiga
Site area:	Approx. 6,600 m ² (Total site area of Hikone Plant is approx. 142,000 m ² .)
Building area:	Approx. 3,900 m ²
Gross floor space:	Approx. 11,200 m ²
Construction:	3-story ferroconcrete structure
Total cost:	About 8 billion yen
Start of construction:	April 2007
Date operations commence:	April 2008
Intended use:	Research and development of semiconductor manufacturing processes